

DARNO\2216\021714205\FSGALG03.DwgPchMaurNDKXVWG

8

7

DARNO\26\28\02\07\05\ST\02\27\Q

6

5

4

3

2

1

REV

DCN NUMBER

DESCRIPTION

ORIGINATOR

DATABASE FILE NAME

GERBER FILE NAME

INCORPORATOR

DATE

00

A44863

INITIAL RELEASE

THJANG

N/A

N/A

THJANG

10/13/99

01

A48943

ADDED 580 & 680 FOOTPRINT

SHPAK

N/A

N/A

SHPAK

09/25/00

02

C17076

CAP TOLERANCE WAS 33.70 +0.50/-0.05
AVAILABLE MARKING AREA WAS 30.60
ADDED 6 LYR TO SCHEDULE, NEW FORMAT

DARNO

N/A

N/A

DARNO

06/28/02

7.

REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234; PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062; MARKING.
C. THIS DRAWING CONFORMS TO THE JEDEC REGISTERED OUTLINE MS-034/A VARIATION AAR-1.

6.

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5.

DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4.

THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 1156.

3.

THE MAXIMUM SOLDER BALL MATRIX SIZE IS 34 X 34.

2.

THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

1.

ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN MILLIMETERS

DECIMAL
X.X ±0.1
X.XX ±0.05
X.XXX ±0.030

ANGULAR
±1°

INTERPRET DIM AND TOL PER
ASME Y14.5M - 1994

MATERIAL
SEE CROSS SECTION

FINISH
SEE NOTE 1

DO NOT SCALE DRAWING

THIRD ANGLE
PROJECTION

APPROVALS

DATE

DESIGNED
D. ARNOLD

08/02/99

CHECKED
M. CUMMINS

08/02/99

PRODUCT MANAGER
D. ARNOLD

08/02/99

RELEASED
SO. KANG

10/13/99

Amkor Technology, Inc.
Chandler, Arizona, USA
Amkor Semiconductor, Inc.,
Suwon, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

mkor/

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NAM

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TITLE
PACKAGE OUTLINE - PBGA CUSTOM, 34 X 34 MATRIX,
35.00mm X 35.00mm, 33.70mm X 33.70mm X 1.17mm -
MOLD CAP, 1.00mm PITCH, LAMINATE SUBSTRATE, AWW

SIZE
A3

TOLERANCE
N/A

DRG NUMBER
N/A

REV
02

PKG OUTLINE DRWG NO.
N/A

SCALE
NONE

SHEET
1 OF 4

FORM NO. MFLA00101.DWG

8

7

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4

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2

1